12500 TI Boulevard, MS 8640, Dallas, Texas 75243

# PCN# 20260421004.1
# Qualify New Assembly Material set for Selected Device(s)
# Change Notification / Sample Request

**Date:** April 21, 2026
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

**20260421004.1**
**Change Notification / Sample Request**
**Attachments**

## Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

| DEVICE | CUSTOMER PART NUMBER |
|---|---|
| SN65LBC174AMDWREP | NULL |
| MSP430F2274MDATEP | MSP430F2274MDATEP |

Technical details of this Product Change follow on the next page(s).

| | | | |
|---|---|---|---|
| **PCN Number:** | 20260421004.1 | **PCN Date:** | April 21, 2026 |
| **Title:** | Qualify New Assembly Material set for Selected Device(s) | | |
| **Customer Contact:** | Change Management team | **Dept:** | Quality Services |
| **Proposed 1st Ship Date:** | July 20, 2026 | **Sample requests accepted until:** | June 20, 2026 |

***Sample requests received after** June 20, 2026 **will not be supported.**

**Change Type:**

| | | | | | |
|---|---|---|---|---|---|
| ☐ | Assembly Site | ☐ | Design | ☐ | Wafer Bump Material |
| ☐ | Assembly Process | ☐ | Data Sheet | ☐ | Wafer Bump Process |
| ☒ | Assembly Materials | ☐ | Part number change | ☐ | Wafer Fab Site |
| ☐ | Mechanical Specification | ☐ | Test Site | ☐ | Wafer Fab Material |
| ☐ | Packing/Shipping/Labeling | ☐ | Test Process | ☐ | Wafer Fab Process |

## PCN Details

**Description of Change:**

Texas Instruments is pleased to announce the qualification of new assembly material for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

**Group 1** (TSSOP)

| | Current | Proposed |
|---|---|---|
| Mount compound | 4042500 | 4147858 |
| Mold compound | 4209002 | 4211471 |

**Group 2** (SOIC)

| | Current | Proposed |
|---|---|---|
| Mount compound | 4042500 | 4147858 |
| Mold compound | 4205694 | 4211880 |

**Reason for Change:**

Continuity of supply.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

Review the SDP for full evaluation of the change based on the customer use case.

**Impact on Environmental Ratings:**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

| RoHS | REACH | Green Status | IEC 62474 |
|---|---|---|---|
| ☒ No Change | ☒ No Change | ☒ No Change | ☒ No Change |

**Changes to product identification resulting from this PCN:**

None

**Group 1 Product Affected:**

| | |
|---|---|
| MSP430F2274MDATEP | V62/08631-01YE |

**Group 2 Product Affected:**

| | | |
|---|---|---|
| CLVCC3245AIDWREP | SN74LVT8980AIDWREP | V62/04755-05YE |
| V62/05602-01ZE | V62/03668-01XE | TLE2024QDWREP |
| LT1014DMDWREP | TLC1543QDWREP | V62/04755-06YE |
| V62/09614-01XE | V62/04647-01XE | TLE2144MDWREP |
| SN65LBC174AI1DWREP | TLC2543QDWREP | V62/08620-03YE |
| SN65LBC174AMDWREP | V62/03614-01XE | TLV5619QDWREP |
| V62/07611-01XE | TLE2024AQDWREP | V62/03615-01XE |

## Group 1 Qualification Report

As per JESD47L guidelines

Approve Date 06-June-2025

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: CVMEH22501AMDGGREP |
|---|---|---|---|---|---|
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | 1/77/0 |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder; | - | 1/22/0 |
| FTY | E6 | Final Test Yield | - | - | 1/1/0 |

Qual Device CVMEH22501AMDGGREP is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com
TI Qualification ID: R-CHG-2408-048

# Group 2 Qualification Report

Approve Date 29-MAY -2025

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: OPA2333AMDREP | Qual Device: OPA4872MDREP | Qual Device: SN65HVD1792TDEP | QBS Reference: SN65HVD1781AQDRQ1 |
|---|---|---|---|---|---|---|---|---|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | - | 3/231/0 |
| UHAST | A3 | Autoclave | 121C/15psig | 96 Hours | - | - | - | 3/231/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | 1/77/0 | 1/77/0 | 1/77/0 | 3/231/0 |
| HTSL | A6 | High Temperature Storage Life | 175C | 500 Hours | - | - | - | 1/45/0 |
| HTOL | B1 | Life Test | 125C | 1000 Hours | - | - | - | 2/154/0 |
| HTOL | B1 | Life Test | 140C | 480 Hours | - | - | - | 1/77/0 |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder; | - | 1/22/0 | - | - | - |
| PD | C4 | Physical Dimensions | Cpk>1.67 | - | - | - | - | 3/30/0 |
| ESD | E2 | ESD CDM | - | 1500 Volts | - | - | - | 1/3/0 |
| ESD | E2 | ESD HBM | - | 16000 Volts | - | - | - | 1/3/0 |
| ESD | E2 | ESD HBM | - | 4000 Volts | - | - | - | 1/3/0 |
| LU | E4 | Latch-Up | Per JESD78 | - | - | - | - | 1/6/0 |
| CHAR | E5 | Electrical Distributions | Cpk>1.67 Room, hot, and cold | - | - | - | - | 3/90/0 |
| FTY | E6 | Final Test Yield | - | - | 1/1/0 | 1/1/0 | 1/1/0 | - |

QBS: Qual By Similarity, also known as Generic Data
Qual Device OPA2333AMDREP is qualified at MSL1 260C
Qual Device OPA4872MDREP is qualified at MSL2 260C
Qual Device SN65HVD1792TDEP is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2408-049

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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